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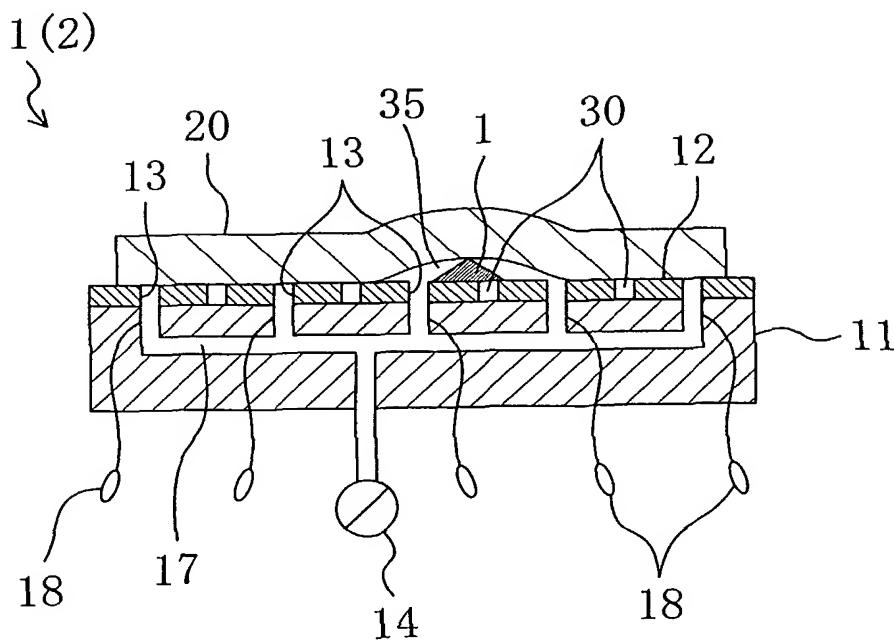
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(54) Title: SUBSTRATE ADSORPTION DEVICE AND SUBSTRATE BONDING DEVICE



(57) Abstract: A substrate adsorption device 1 includes: a stage 11 having an adsorption face 12 for holding a substrate 20; a plurality of adsorption ports 13 formed in a region of the adsorption face 12 of the stage 11; and a vacuum pump 14 connected to each adsorption port through an air discharge path 17. A pressure sensor 18 for detecting the pressure in the air discharge path 17 is provided, and a plurality of leak trenches 30 open to both the adsorption face 12 of the stage 11 and a side face of the stage 11 are formed in a region of the stage 11 except the region where the adsorption ports 13 are formed. With such a low-cost and simple structure, a foreign matter 15, which is a factor of inviting damage to the substrate 20, is detected, to prevent damage to the substrate 20.